| L | Hits | Search Text | DB | Time stamp |
|--------|--------|--|---|------------------|
| Number | | | USPAT; | 2002/09/30 |
| 1 | 459667 | wafer chip die dice | US-PGPUB | 10:30 |
| | | (wafer chip die dice) and (quality near10 | USPAT; | 2002/09/30 |
| 2 | 4473 | | US-PGPUB | 10:31 |
| | 0710 | test\$3) ((wafer chip die dice) and (quality | USPAT; | 2002/09/30 |
| 3 | 2718 | near10 test\$3)) and chip | US-PGPUB | 10:31 |
| | 1220 | (((wafer chip die dice) and (quality | USPAT; | 2002/09/30 |
| 4 | 1339 | near10 test\$3)) and chip) and memory | US-PGPUB | 09:20 |
| _ | 702 | ////wafer chip die dice) and (quality | USPAT; | 2002/09/30 |
| 5 | 702 | near10 test\$3)) and chip) and memory) and semiconductor | US-PGPUB | 09:21 |
| 8 | 111 | ((((wafer chip die dice) and (quality | US-PGPUB | 2002/09/30 |
| 0 | | near10 test\$3)) and chip) and memory) and semiconductor | | 09:21 |
| 6 | 591 | ((()) (wafer chip die dice) and (quality | USPAT | 2002/09/30 |
| | | near10 test\$3)) and chip) and memory) and semiconductor | į. | 09:45 |
| 9 | 39675 | semiconductor near10 chip | USPAT | 2002/09/30 |
| " | 330,0 | | | 09:46 |
| 10 | 13489 | (semiconductor near10 chip) and test\$3 | USPAT | 2002/09/30 |
| | | | | 09:46 |
| 11 | 6216 | ((semiconductor near10 chip) and test\$3) | USPAT | 2002/09/30 |
| | | and (dic\$3 singulat\$3 divid\$3) | *************************************** | 10:34 2002/09/30 |
| 12 | 5443 | (((semiconductor near10 chip) and test\$3) | USPAT | 09:48 |
| | | and (dic\$3 singulat\$3 divid\$3)) and | | 09.40 |
| | | result | USPAT | 2002/09/30 |
| 13 | 79 | ((semiconductor near10 chip) and test\$3) and (test\$3 near20 result\$3 near50 (dic\$3 | USFAI | 10:26 |
| | | and (test\$3 near20 result\$3 hear30 (dre\$5 singulat\$3 divid\$3)) | | 10.20 |
| | 502076 | | EPO; JPO; | 2002/09/30 |
| 14 | 593876 | water chip die dice | DERWENT; | 10:31 |
| | | | IBM TDB | |
| 15 | 414 | (wafer chip die dice) and (quality near10 | EPO; JPO; | 2002/09/30 |
| 13 | 414 | test\$3) | DERWENT; | 10:31 |
| | | | IBM_TDB | |
| 16 | 246 | ((wafer chip die dice) and (quality | EPO; JPO; | 2002/09/30 |
| • | | near10 test\$3)) and chip | DERWENT; | 10:33 |
| | | | IBM_TDB | |
| 17 | 63267 | semiconductor near10 chip | EPO; JPO; | 2002/09/30 |
| | | | DERWENT; | 10:33 |
| | | • | IBM_TDB | 2002/00/20 |
| 18 | 3803 | (semiconductor near10 chip) and test\$3 | EPO; JPO; | 2002/09/30 |
| | | | DERWENT; | 10:33 |
| | | | IBM_TDB EPO; JPO; | 2002/09/30 |
| 19 | 264 | | DERWENT; | 10:34 |
| | | and (dic\$3 singulat\$3 divid\$3) | IBM TDB | 10.34 |
| L | 1 | | I I DEL I DE | |